

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of: Francis Bourrieres, Clement Kaiser
Application No.: 09/830253
Filed: April 24, 2001
For: Method For Making Electronic Mod
Integrated Preforms Capable of Bein
Implementing Device
Examiner: Minh Trinh
Group Art Unit: 3729

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GROUP 3700

Commissioner for Patents
Washington, D.C. 20231

Docket No.: N48-2-9735-US01

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TO: Examiner Trinh

DATE: January 24, 2003

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Following please find a Second Preliminary Amendment for the above-identified application.

If a fee is required, Commissioner of Patents is hereby authorized to charge Deposit Account No. 22-0350 for any required fees.

Respectfully Submitted,

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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	Francis Bourrieres, Clement Kaiser
Application No.:	09/830253
Filed:	April 24, 2001
For:	Method For Making Electronic Modules With Ball Connector Or With Integrated Preforms Capable Of Being Soldered On A Printed Circuit And Implementing Device
Examiner:	Minh Trinh
Group Art Unit:	3729

Box _____
Assistant Commissioner for Patents
Washington, D.C. 20231

Docket No.: N48.2I-9735-US01

Second Preliminary Amendment

Prior to examination, please amend the application as follows:

In The Claims:

Please amend the claims as follows:

1) (Amended twice) Method for producing an electronic module in the shape of a ball housing combining a network of balls (7) or geometrically identical preform connectors or shield system and surface-mounted components (2) on the same side of a substrate (1), thus making this module directly connectable to a printed circuit (3), wherein

soldering cream (8) is deposited simultaneously for the components and the connecting ball or shield system located on the same surface;

said components are transferred onto the corresponding mounting lands;

the ball connectors are transferred collectively onto the lands of the same side intended for them by an appropriate device; and

a single re-melting cycle permits simultaneous soldering of the components and the connecting balls or shields onto the substrate.